

Abstract of the Disclosure

A method and apparatus for inspection of probe marks made on the interconnection lands of semiconductor devices using machine vision is disclosed. An image of an interconnection land is analyzed, and features of the image that may constitute indicia of probe marks are refined through the application of a series of unique heuristic processes. The output of the method is measurement data that can be used to characterize and verify the processes used to electrically probe semiconductor devices.

Cognex Confidential